

FEMTOSECOND LASER IRRADIATION FOLLOWED BY CHEMICAL ETCHING - VERSATILE METHOD FOR FABRICATION OF INNOVATIVE 3D STRUCTURES IN GLASS MATERIALS

Sylwester Bargiel^{1*}, Chibundo Nwafor¹, Bhawnath Tiwari¹, Ting-Ting Wang^{1,2}, Kanty Rabenorosoa¹,
Guillaume Laurent¹, Joël Agnus¹, Cedric Clévy¹, Vincent Laude¹, Christophe Gorecki¹
¹FEMTO-ST Institute, UMR6174 CNRS, Université Franche-Comté, Besançon, France
²Institute of Engineering Mechanics, Beijing Jiaotong University, 100044 Beijing, China
*sylwester.bargiel@femto-st.fr

Keywords : 3D machining, Glass, femtosecond laser machining, wet etching, FLICE

The glass materials are widely used in the microsystems technology due to attractive combination of their excellent physical and chemical properties, long-term stability, close CTE match to Si, and relatively low cost of high quality substrates. Various applications take advantage of their remarkable optical transmission (MOEMS, gas microcells for time-frequency devices), natural hydrophilicity and biocompatibility (Lab-on-chip, Bio-MEMS), good electrical insulation (micro-sensors) or high thermal/chemical resistance (microreactors). However, the micromachining of glass is challenging because of its high hardness and brittleness as well as easy crack formation. Great effort has been made to develop new laser-based methods, capable of overcoming these technological challenges for new emerging applications, such as microrobotics for minimally invasive surgery [1], where small structures with 3D complex geometries need to be fabricated.

The subtractive machining by femtosecond laser irradiation followed by chemical etching (FLICE) is one of the recently developed hybrid methods that has proved to be a powerful tool for 3D glass micromachining [2,3]. The FLICE process relies on the local and permanent modification of glass caused by high-energy focused laser beam irradiation (Fig.1a). At specific set of process parameters, high increase of etch rate of irradiated glass (typ. x200) may be observed in standard etchant (HF, KOH). Depending on writing objective, complex high aspect (AR>40) structures may be obtained with high spatial resolution (typ. 1.5 μ m in XY plane, 8-40 μ m in Z-axis) and in relatively thick glass layers, up to few millimeters. In this work, a great potential of FLICE method will be demonstrated on the example of various devices, fabricated in different glass materials (Fig. 1b-e). Characteristic features of FLICE machining and some process limitations will be also presented.

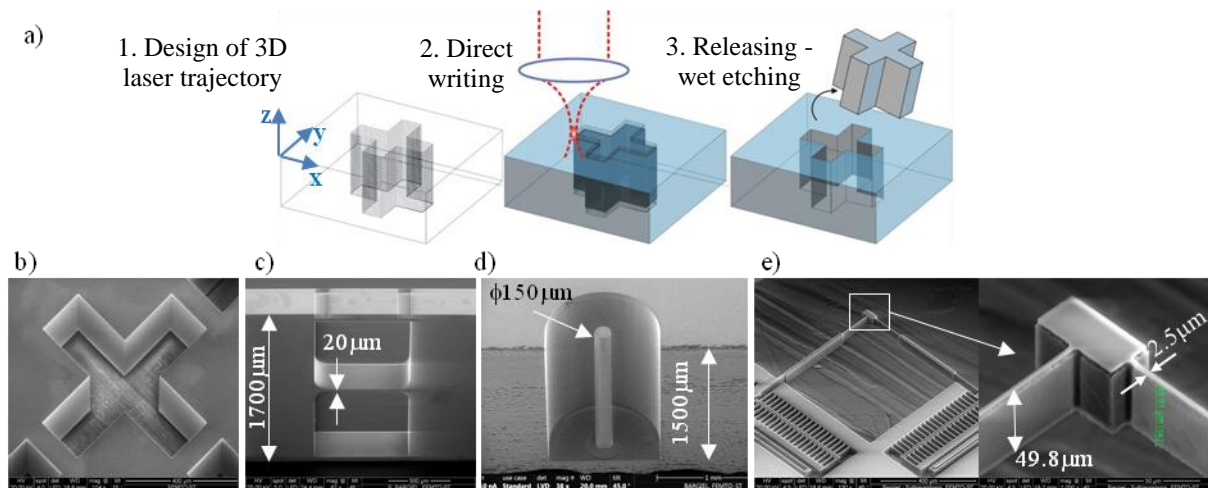


Figure 1. Main fabrication steps of the FLICE method (a) and some examples of microstructures: 15 μ m-thick membrane at the bottom of 500 μ m substrate (b), flexible part of glass microgripper with 20 μ m-thick central spring (c), 1500 μ m high glass rod with diameter of 150 μ m (d), transparent platform with high aspect ratio suspensions (AR=20) to be driven by comb-drive actuators.

This work was supported in part by the COLAMIR project (ANR-16-CE10-0009), in part by the EIPHI Graduate School (ANR-17-EURE-0002) and partially by French RENATECH network and its FEMTO-ST technological facility.

- [1] L. S. Mattos *et al.*, “ μ RALP and Beyond: Micro-Technologies and Systems for μ Robot-Assisted Endoscopic Laser Microsurgery,” *Front. Robot. AI*, vol. 8, no. September, pp. 1–19, 2021.
- [2] A. Marcinkevicius *et al.*, “Fabrication of 3D interconnected network of microchannels inside silica by femtosecond irradiation and etching”, *Laser Applications in Microelectronic and Optoelectronic Manufacturing VI*, Proceedings of SPIE, vol. 4274, pp. 469–477, 2001
- [3] B. Lenssen and Y. Bellouard, “Optically transparent glass micro-actuator fabricated by femtosecond laser exposure and chemical etching”, *Applied Physics Letters*, vol. 101, no. 10, pp. 1–5, 2021.
- [4] T. Wang, S. Bargiel, F. Lardet-Vieudrin, Y. Wang, Y. Wang, and V. Laude, “Collective Resonances of a Chain of Coupled Phononic Microresonators,” *Phys. Rev. Appl.*, vol. 13, p. 10, 2020.